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(54) Title: COATING COMPONENTS FOR SEMICONDUCTOR PROCESSING WITH FLUORINE-CONTAINING MATERIALS

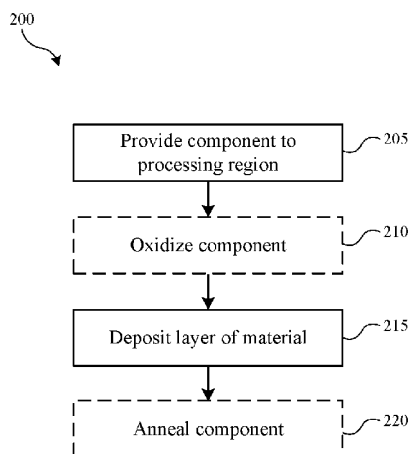


FIG. 2

(57) Abstract: Exemplary processing methods may include providing a component for semiconductor processing to a processing region of a processing chamber. The methods may include providing one or more deposition precursors to the processing region. The one or more deposition precursors may include a metal-containing precursor and a fluorine-containing precursor. The methods may include depositing a layer of material on the component for semiconductor processing in the processing region. The layer of material comprises a metal-and-fluorine-containing material.

